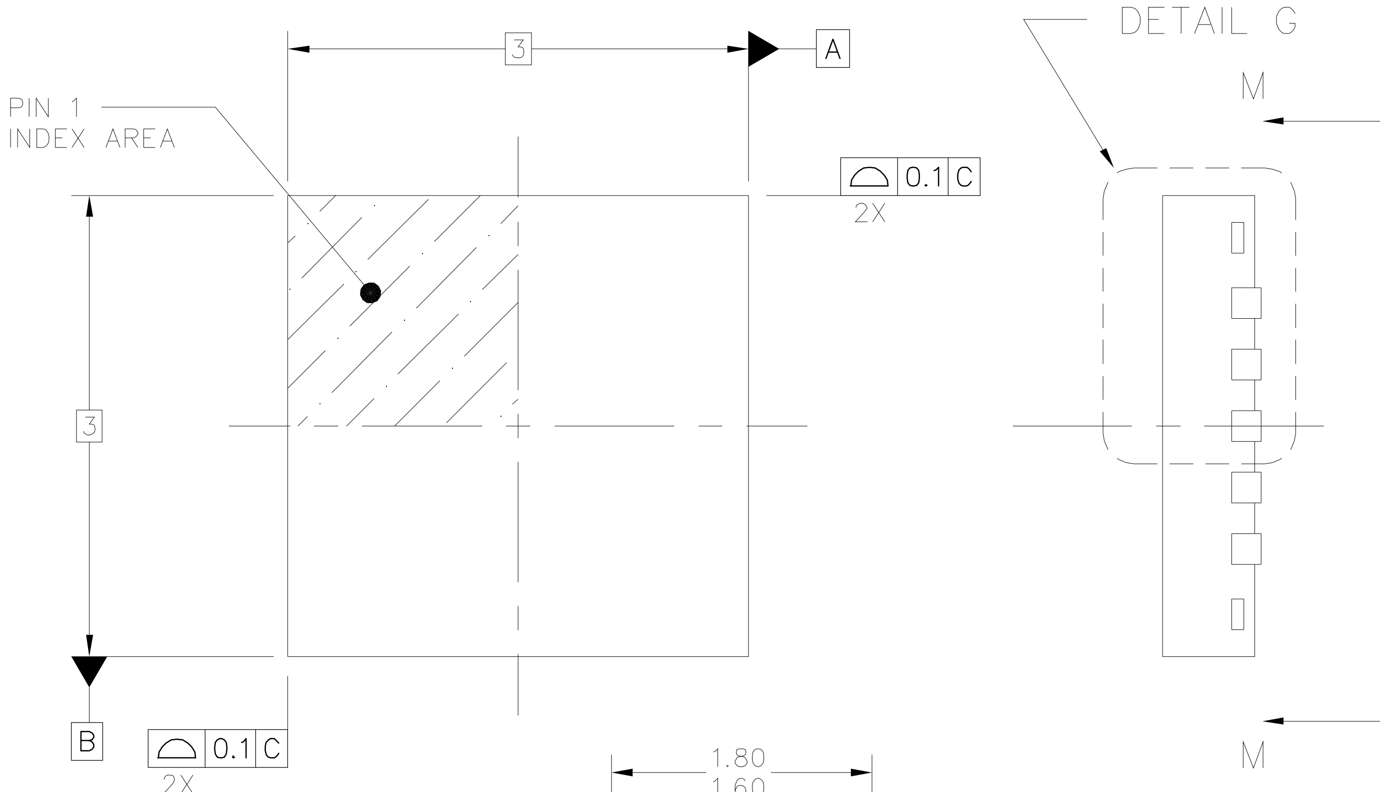
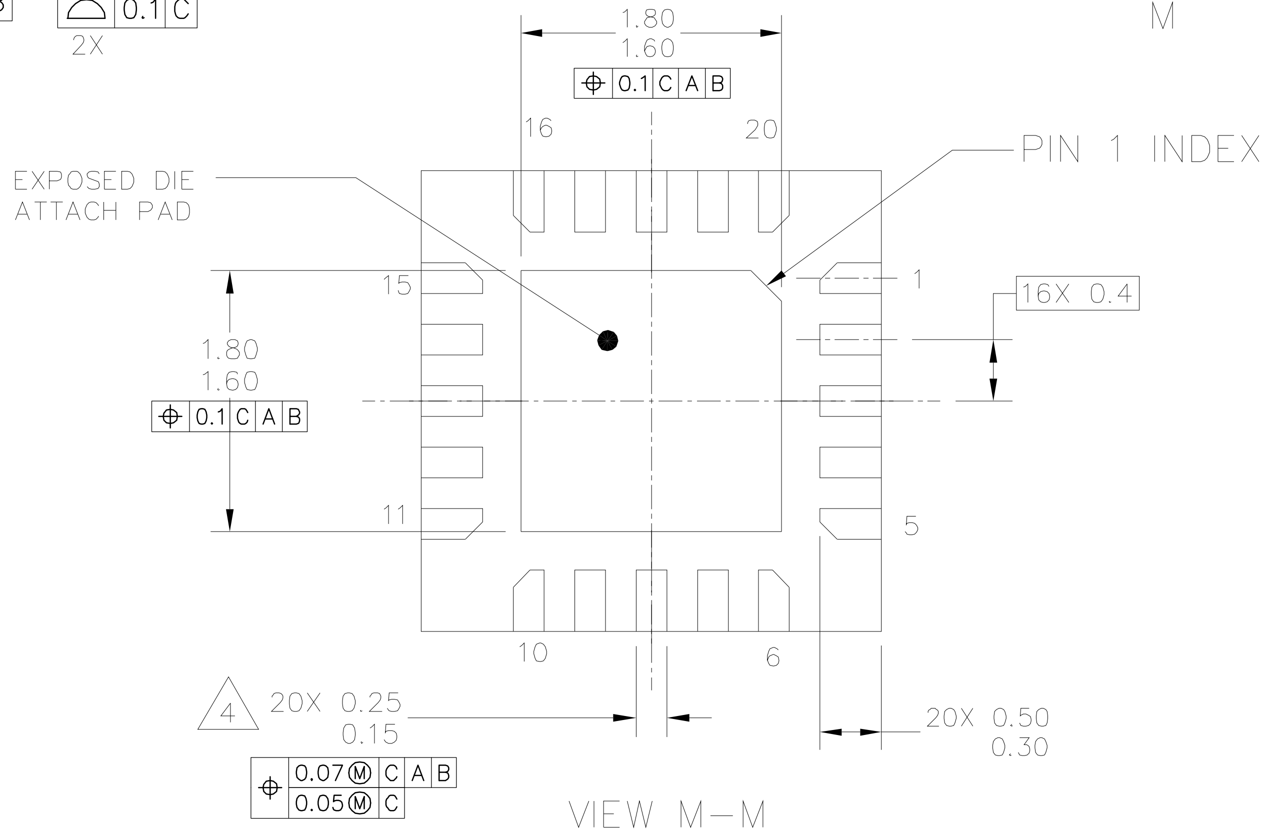
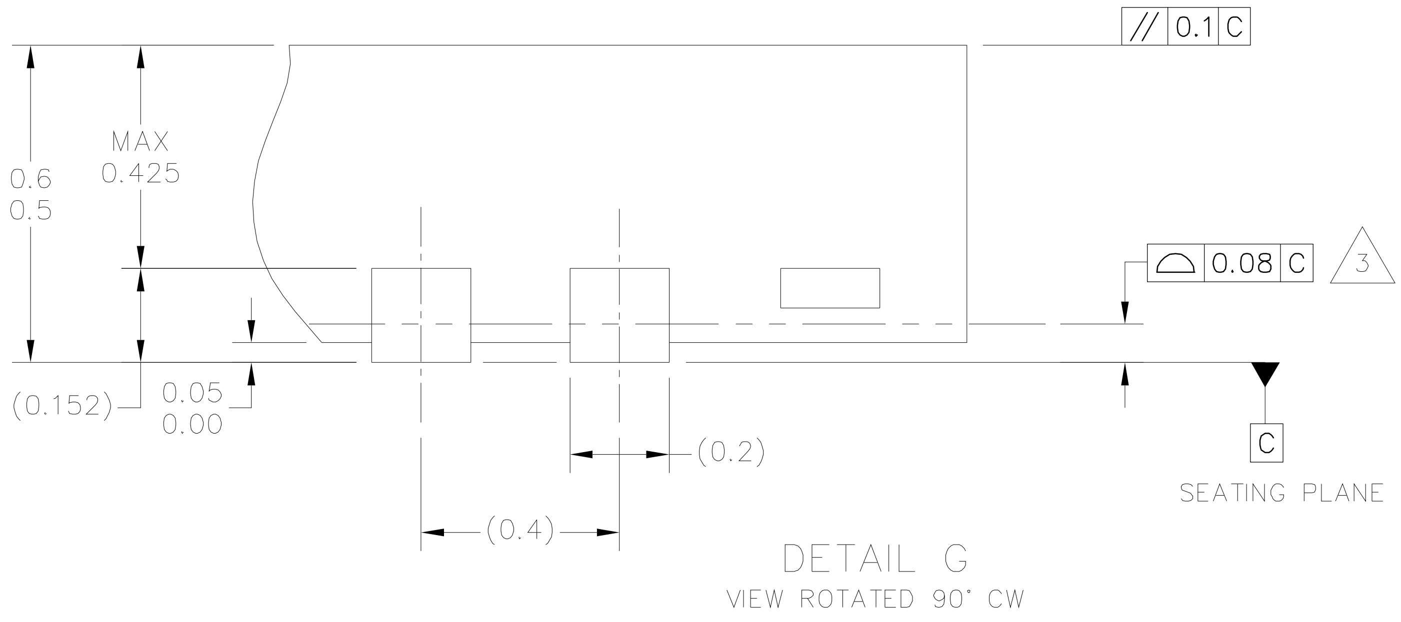




© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED QUAD FLAT NON–LEADED PACKAGE (QFN) 20 TERMINAL, 0.4 PITCH (3 X 3 X 0.6) EXPOSED LEAD END CASE OUTLINE	DOCUMENT NO: 98ARE10742D	REV: A
	STANDARD: NON–JEDEC	
	SOT1628–1	03 FEB 2016



© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 20 TERMINAL, 0.4 PITCH (3 X 3 X 0.6) EXPOSED LEAD END CASE OUTLINE	DOCUMENT NO: 98ARE10742D	REV: A
	STANDARD: NON-JEDEC	
	SOT1628-1	03 FEB 2016

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.

4. DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 MM AND 0.25 MM FROM TERMINAL TIP.

5. MIN. METAL GAP SHOULD BE 0.2MM.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 20 TERMINAL, 0.4 PITCH (3 X 3 X 0.6) EXPOSED LEAD END CASE OUTLINE	DOCUMENT NO: 98ARE10742D	REV: A
	STANDARD: NON-JEDEC	
	SOT1628-1	03 FEB 2016